

Zwipe Pay

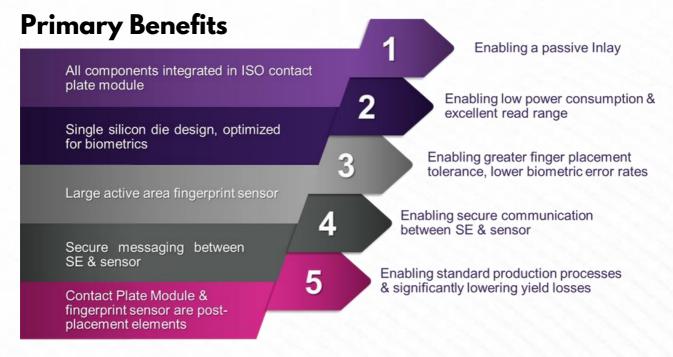
Product Brief

Zwipe Pay is a biometric payment solution. Biometric feature extraction and comparison is performed within the secure element, on a single die. The primary application is for biometric payment cards and wearable devices. Zwipe Pay consists of three key components:

- · an IC module with biometric secure element
- · a fingerprint sensor
- a passive inlay, just like a standard dual interface card inlay.

The IC module and fingerprint sensor can be embedded into the card body after lamination. There are no active electronics on the inlay, reducing cost and increasing reliability.

Passive inlays come on prelaminated sheets, made to smart card manufacturer specifications. These prelaminates enable hot lamination in a standard card manufacturing process.



Certifications

- EMVCo™
- CQM compliance

Specification Compliance

- Visa VBSS 1.0.1
- Mastercard M/Chip Advance Biometric Application Specification 1.2.3



Technical Data

IC module

Module Design:

Offset -6

Outer Dimensions:

o 12.8 mm x 11.6 mm ± 0.2 mm

Plating:

Gold or Palladium (see right)

Bond pads (#)

o 6 active, 2 mechanical

Bonding method:

• ACF (Dexerials EH1038-40 recommended)

Secure Element:

• IDEMIA StarChip SCR496U

Interfaces:

• ISO/IEC 7816-3, Class A & B • ISO/IEC 14443, Type A

Flash Memory:

496 k Byte

OS:

 GlobalPlatform Financial Configuration / Java Card compliant



Fingerprint Sensor



Sensor manufacturer & model:

IDEX Biometrics IDX3405

Sensing technology:

Off-chip capacitive

Sensor dimensions:

• 16.2 mm x 16.2 mm ± 0.1 mm

Active sensing area:

o 9.5 mm x 9.5 mm

Security:

Secure messaging to SE

Current consumption:

o < 5 mA

Bond pads (#):

4 active, 4 mechanical

Bonding method:

• ACF (Dexerials EH1038-40 recommended)

Prelaminate

Inlay type:

o Passive, embedded wire

Substrate material:

o PVC, white

Prelaminate geometries:

To customer specification

Prelaminate thickness:

320 μm ± 20μm

